

Abstract

A method for mounting through an anisotropic conductive film 5 defined as an adhesive sheet an electronic component 3 on a printed board (flexible board 1) provided with a wiring pattern 2. The anisotropic conductive film 5 is bonded to an area of the flexible board 1 to be mounted with the electronic component 3 in a state where air intervening between the anisotropic conductive film 5 and the flexible board 1 is heated. Since the air confined between the anisotropic conductive film and the flexible board reduces in volume upon cooled down, occurrence of voids, exposure of the wiring pattern, or the like is avoided. Consequently, reliability can be enhanced without complicating the mounting.